

**Specification Details:**

Specification: MIL-PRF-38534  
Title: Hybrid Microcircuits  
Federal Supply Class (FSC): 5962  
Conventional: No  
Specification contains quality assurance program: Yes  
MIL-STD-790 Established Reliability & High Reliability: No  
MIL-STD-690 Failure Rate Sampling Plans & Procedures: No  
Weibull Graded: No  
Specification contains space level reliability requirements: Yes  
Specification allows test optimization: Yes

**Contact Information:**

Office of Primary Involvement: Hybrid Devices Branch, DLA Land and Maritime - VQH  
Primary Qualifying Activity Contact: 614-692-0596, e-mail: vqh.rb@dla.mil  
Secondary Qualifying Activity Contact: 614-692-0582, e-mail: vqh.esr@dla.mil

**Notes:**

In order for a manufacturer to have test data considered for qualification, the manufacturer must perform all required qualification tests; produce the qualification sample with DLA Land and Maritime-VQ certified materials and manufacturing construction techniques; and comply with the requirements specified in MIL-PRF-38534.

Custom hybrid microcircuit materials and manufacturing construction techniques in this listing applies only to products produced on the MIL-PRF-38534 certified line(s) at the plant(s) specified in this listing.

Custom hybrid microcircuits manufactured, assembled, and tested in accordance with MIL-PRF-38534 shall bear the "certification mark" for SMD controlled hybrid Microcircuits, or the "compliant hybrid" certification mark for non-SMD controlled hybrid microcircuits as follows:

SMD product, for all classes, shall have the certification mark "QML" or "Q" for small devices.  
Non-SMD product dated after MIL-PRF-38534D, for Class K shall have the certification mark "CK."  
Non-SMD product dated after MIL-PRF-38534D, for Class H shall have the certification mark "CH."  
Non-SMD product dated after MIL-PRF-38534D, for Class G shall have the certification mark "CG."  
Non-SMD product dated after MIL-PRF-38534D, for Class E shall have the certification mark "CE."  
Non-SMD product dated after MIL-PRF-38534D, for Class D shall have the certification mark "CD."  
Non-SMD dated prior to MIL-PRF-38534D, for all classes, shall have the certification mark "CH" or "C" for small devices.

These certification marks or the abbreviations "Q" or "C" shall not be used on product that does not meet all requirements of MIL-PRF-38534 except as allowed in 3.7.5 of MIL-PRF-38534.

Products manufactured, assembled, and tested for Class K, Class H, Class G, Class E, or Class D, with all the provisions of MIL-PRF-38534, and with DLA Land and Maritime-VQ qualified materials and manufacturing construction techniques, can be represented as being compliant to the appropriate product assurance levels as listed herein. The information contained in this listing reflects the general material and manufacturing techniques of the particular test sample(s). In order to protect the manufacturers' proprietary processes and materials, only the generic process and material are listed. The user must contact the manufacturer for any detail information on specific materials (i.e., such as epoxy, getter, solder-type), or process details. Processes and materials, not listed, may be considered qualified by similarity to those demonstrated for the qualification (e.g., different wire, package, or die sizes). See Appendix E of MIL-PRF-38534, Class I, major changes paragraph, for a baseline of qualification limits.

Any product represented as being compliant to MIL-PRF-38534 must be built using qualified processes and materials. The user shall be responsible for determining if the qualification baseline for a given class level is adequate to demonstrate capability for the intended application.

To obtain MIL-PRF-38534 qualified hybrid microcircuits, the user should specify in the procurement document that the product be manufactured to MIL-PRF-38534, and be comprised of materials and manufacturing construction techniques listed herein. Acquisition requirements are contained in paragraph 6.2 of MIL-PRF-38534. Microcircuit devices represented as being built, tested and shipped under the QML provision of MIL-PRF-38534 must be built using qualified manufacturing materials and construction in this listing.

Contractor acquiring activities, military program offices, and other government representatives can determine if hybrid microcircuits meet the requirements of MIL-PRF-38534 by:

- a. For SMD controlled product: Product listed in the product eligibility section herein and marked with "QML" or "Q".
- b. For non-SMD controlled Product: The part will not be listed herein. However, the part will be marked with "C" plus the Class Level designator".

WARNING! If products were not purchased to, and identified as MIL-PRF-38534 compliant, do not assume they have been manufactured on the DLA Land and Maritime-VQ certified line, with qualified materials and processes, or that all other MIL-PRF-38534 requirements were performed. To determine whether new SMD controlled products are in accordance with MIL-PRF-38534, or to verify any new process/material qualifications, you may call the qualifying activity (DLA Land and Maritime-VQ).

DLA Land and Maritime-VQ ISO Registrations are also listed herein. However, QML listed manufacturers may have ISO registrations from other registrars.

1/ This listing can be expanded provided appropriate qualification testing is performed and passed. Therefore the manufacturer may accept an order for compliant product not covered by his listing, but shall not ship the compliant product until the testing has been successfully completed.

2/ Package seal perimeter is listed by largest perimeter successfully tested in inches.

3/ Package lead counts are listed by maximum number of leads covered by qualification.

4/ Caution. Do not use this number for item acquisition. Item acquired to this number may not satisfy the performance requirements of the listed SMD.

5/ Inactive for new design, no longer available from manufacturer.

6/ Class E devices are devices which meet all of the requirements of one of the other classes (K, H, or G), with some exceptions taken. Therefore any manufacturer qualified to G, H or K is eligible to produce and mark product as compliant to class E.

**Part Configuration:**

Standardized Microcircuit Drawing (SMD)

5962	99616	01	H	X	A
Federal Stock Class	SMD Number	Device Number	Class	Package Type	Lead Finish

**Process/Material Listings:**

**Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH**

**DLA Land and Maritime - VQ**

**MIL-PRF-38534 QML Program Status**

**Aeroflex Microelectronic Solutions (CAGE Code: 88379)**

35 South Service Road, Plainview, NY 11803-4193, US

**Company Contact:** Mr. Joe Mazzotta, Phone: 516-752-2359, Fax: 516-694-6715, E-mail: Joe.Mazzotta@aeroflex.com

**DSCC Contact:** Ms. Jacqueline Cunningham, Phone: 614-692-0584, Fax: 614-692-6942, E-mail: vqh.jc@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Linear, Analog, Digital, Power, Voltage Regulator

**Aeroflex Microelectronic Solutions**

**Qualification Letters:** EQ(EQC-90-616), EQ(EQC-91-896), EQ(EQC-92-001), EQ(EQC-93-019), EQ(EQC-94-032), ELS(ELSH-94-0342), ELS(ELSH-95-0042), ELS(ELSH-95-0395), ELS(ELSH-96-0130), ELS(ELSH-96-176), VQ(VQH-98-0001), VQ(VQH-99-0028), VQ(VQH-01-0070), VQ(VQH-01-0081), VQH-02-000431, VQ(VQH-02-001027), VQ(VQH-04-5086), VQ(VQH-04-005472), VQ(VQH-04-006026), VQ(VQH-04-006367), VQ(VQH-05-008607), VQ(VQH-05-009404), VQ(VQH-06-010542), VQ(VQH-07-012806), VQ(VQH-11-022595), VQ(VQH-13-025566)

**Class Level Information: See Note 6/**

Class K, Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** QAP21-225, QAP21-240

**Substrate Fabrication:** Thick Film on Alumina, 6 Conductor Level(s), Resistors; Thick Film on Beryllia, 1 Conductor Level(s)

**Assembly Information: See Note 1/**

**Assembly Flows:** QAP21-241, QAP21-337

**Substrate Attach:** Solder, Nonconductive Epoxy, Conductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Solder, Eutectic

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Tantalum Capacitors, Tabs, Chip Resistors, Daughter Board, Transformers, Optocoupler Assembly

**Wire Bonding:** Gold, Aluminum

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Axial Leads, Seam Weld, 7.94 Inch Seal Perimeter, 90 Leads, Gold Lead Finish; Ceramic Package, Dual-in-line, Seam Weld, 3.72 Inch Seal Perimeter, 24 Leads, Gold Lead Finish; Metal Package, Peripheral Leads, Seam Weld, 7.01 Inch Seal Perimeter, 88 Leads, Gold/Solder Lead Finish; Metal Package, Platform, Projection Weld, 3.93 Inch Seal Perimeter, 24 Leads, Gold Lead Finish; Ceramic Co-fire Package, Axial Leads, Seam Weld, 7.66 Inch Seal Perimeter, 90 Leads, Gold Lead Finish; Metal Package, Flatpack, Seam Weld, 5.00 Inch Seal Perimeter, 96 Leads, Gold Lead Finish; Ceramic Package, Leadless Chip Carrier, Seam Weld, 1.39 Inch Seal Perimeter, 5 Leads, Gold Lead Finish; Ceramic Co-fire Package, Axial Leads, Solder Seal, 1.43 Inch Seal Perimeter, 16 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

***Aeroflex Microelectronic Solutions (CAGE Code: 88379)***

35 South Service Road, Plainview, NY 11803-4193, US

**Company Contact:** Mr. Joe Mazzotta, Phone: 516-752-2359, Fax: 516-694-6715, E-mail: Joe.Mazzotta@aeroflex.com

**DSCC Contact:** Ms. Jacqueline Cunningham, Phone: 614-692-0584, Fax: 614-692-6942, E-mail: vqh.jc@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Linear, Analog, Digital, Power, Voltage Regulator

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**Cirtek Electronics Corp. Philippines Plant**

**Qualification Letters:** VQ(VQH-03-003903), VQ(VQH-03-004625)

**Class Level Information:** See Note 6/

Class H

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** N/A

**Assembly Information:** See Note 1/

**Assembly Flows:** QAP21-241

**Substrate Attach:** Nonconductive Epoxy

**Element Attach:** Conductive Epoxy, Eutectic

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Tabs, Chip Resistors

**Wire Bonding:** Gold

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** N/A

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Analog Devices Incorporated (CAGE Code: 34031)**

Assembled Products Division, 7910 Triad Center Drive, Greensboro, NC 27409-9605, US

**Company Contact:** Ms. Elaine Trotter, Phone: 336-605-4234, Fax: 336-605-4347, E-mail: elaine.trotter@analog.com

**DSCC Contact:** Mr. Joseph Buben II, Phone: 614-692-0592, Fax: 614-692-6942, E-mail: vqh.jbu@dla.mil

**Quality Management (QM) Program:** TRB

**Periodic Inspection System:** Option 1

**Approved ISO 9000 System:** No

**Technologies:** AD/DA Converters, Buffer, Op-Amp, Track and Hold, Voltage Reference, Signal Processor, Data Acquisition Systems, DC/DC Converters

**Sub: RF2M Microelectronics Ltd. (Cage: U4388)**

**Qualification Letters:** VQ(VQH-04-006510), VQ(VQH-04-007022), VQ(VQH-04-007023), VQ(VQH-05-008727), VQ(VQH-06-010144), VQ(VQH-09-017847)

**Class Level Information: See Note 6/**

Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Purchased Ceramic Co-fire; Thick Film, 4 Conductor Level(s)

**Assembly Information: See Note 1/**

**Assembly Flows:** FCES 6301:15

**Substrate Attach:** Nonconductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Chip Resistors, Ceramic Tabs, Transformers

**Wire Bonding:** Gold

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Ceramic Co-fire Package, Dual-in-line, Seam Weld, 2.53 Inch Seal Perimeter, 24 Leads, Gold Lead Finish; Ceramic Package, Dual-in-line, Seam Weld, 5.38 Inch Seal Perimeter, 32 Leads, Gold Lead Finish; Ceramic Package, Quad Flat Pack, Seam Weld, 3.48 Inch Seal Perimeter, 68 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Apex Microtechnology Incorporated (CAGE Code: 60024)**

5980 North Shannon Road, Tucson, AZ 85741-5230, US

**Company Contact:** Ms. Karen Gregory, Phone: 520-690-8667, Fax: 520-888-3329, E-mail: Karen.Gregory@apexanalog.com

**DSCC Contact:** Mr. Edward Raybould, Phone: 614-692-0582, Fax: 614-692-6942, E-mail: vqh.esr@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Option 1

**Approved ISO 9000 System:** Yes

**Technologies:** Power Op-Amp

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**Qualification Letters:** EQ(EQC-91-347), EQ(EQC-92-410), EQ(EQC-92-416), EQ(EQC-93-028), EQ(EQC-93-595), ELS(ELSH-94-0354), ELS(ELSH-95-0070)

**Class Level Information: See Note 6/**

Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** Flow 01

**Substrate Fabrication:** Thick Film on Beryllia, 1 Conductor Level(s), Resistors

**Assembly Information: See Note 1/**

**Assembly Flows:** Flow 10, Flow 99

**Substrate Attach:** Solder

**Element Attach:** Conductive Epoxy, Solder

**Add-on Elements:** Unpackaged Die, Chip Capacitors

**Wire Bonding:** Aluminum

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, TO can, Projection Weld, 2.67 Inch Seal Perimeter, 8 Leads, Gold/Solder Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**API Technologies Corp. RF2M UK (CAGE Code: U4388)**

South Denes, Great Yarmouth, Norfolk NR30 3PX, England

**Company Contact:** Mr. Mark Whelband, Phone: 1493-743121, Fax: 1493-858536, E-mail: Mark.Whelband@apitech.com

**DSCC Contact:** Mr. Joseph Buben II, Phone: 614-692-0592, Fax: 614-692-6942, E-mail: vqh.jbu@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Option 1

**Approved ISO 9000 System:** No

**Technologies:** 1553 Transceiver, High Voltage Drivers, Power

**Qualification Letters:** EQ(EQC-91-835), EQ(EQC-92-084), EQ(EQC-93-139), ELS(ELSH-96-0054), ELS(ELSH-96-0161), VQ(VQH-98-0227), VQ(VQH-99-0192), VQ(VQH-99-0196), VQ(VQH-04-006510), VQ(VQH-04-007022), VQ(VQH-04-007023), VQ(VQH-05-008727), VQ(VQH-05-008978), VQ(VQH-06-010730), VQ(VQH-06-011795), VQ(VQH-09-017847), VQ(VQH-10-020173), VQ(VQH-10-020296), VQ(VQH-13-025883), VQ(VQH-14-028390), VQ(VQH-15-028729)

**Class Level Information: See Note 6/**

Class K, Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** FCES 6301:15

**Substrate Fabrication:** Purchased Ceramic Co-fire; Thick Film on Alumina, 4 Conductor Level(s), Resistors; Purchased Direct Bonded Copper on Beryllia

**Assembly Information: See Note 1/**

**Assembly Flows:** FCES 6301:15

**Substrate Attach:** Conductive Epoxy, Nonconductive Epoxy, Solder

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Eutectic

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Chip Resistors, Transformers, Ceramic Tabs

**Wire Bonding:** Gold, Aluminum, Aluminum Ribbon

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Axial Leads, Seam Weld, 5.30 Inch Seal Perimeter, 36 Leads, Gold/Solder Lead Finish; Metal Package, Peripheral Leads, Seam Weld, 5.30 Inch Seal Perimeter, 36 Leads, Gold/Solder Lead Finish; Metal Package, Axial Leads, Projection Weld, 4.37 Inch Seal Perimeter, 24 Leads, Gold/Solder Lead Finish; Ceramic Package, Pin Grid Array, Seam Weld, 5.00 Inch Seal Perimeter, 101 Leads, Gold Lead Finish; Metal Package, TO can, Projection Weld, 1.13 Inch Seal Perimeter, 10 Leads, Gold/Solder Lead Finish; Ceramic Co-fire Package, Dual-in-line, Seam Weld, 2.53 Inch Seal Perimeter, 24 Leads, Gold Lead Finish; Ceramic Package, Dual-in-line, Seam Weld, 5.38 Inch Seal Perimeter, 32 Leads, Gold Lead Finish; Ceramic Package, Quad Flat Pack, Seam Weld, 3.48 Inch Seal Perimeter, 68 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**API Technologies RF/Microwave & Microelectronics (CAGE Code: 27851)**

400 Nickerson Road, Marlborough, MA 01752, US

**Company Contact:** Mr. Gregory Madden, Phone: 508-251-6429, Fax: , E-mail: Gregory.Madden@apitech.com

**DSCC Contact:** Mr. Edward Raybould, Phone: 614-692-0582, Fax: 614-692-6942, E-mail: vqh.esr@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Option 2

**Approved ISO 9000 System:** No

**Technologies:** Low Power, Analog, Voltage Reference, Direct Bond Copper Hybrid

**Qualification Letters:** EQ(EQC-89-421), ELS(ELSH-94-0252), ELS(ELSH-94-0253), ELS(ELSH-94-0254), ELS(ELSH-95-0183), VQ(VQH-98-0177), VQ(VQH-98-0232), VQ(VQH-99-0176), VQ(VQH-99-0204), VQ(VQH-01-0102), VQ(VQH-01-0104), VQ(VQH-03-004619), VQ(VQH-04-004898), VQ(VQH-04-005172), VQ(VQH-06-011842), VQ(VQH-07-013689), VQ(VQH-08-014380)

**Class Level Information: See Note 6/**

Class K, Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** 52-0059

**Substrate Fabrication:** Thin Film on Alumina, 2 Conductor Level(s), Resistors; Thin Film on Alumina, 1 Conductor Level(s); Thin Film on Beryllia, 1 Conductor Level(s); Purchased Direct Bonded Copper on Alumina Nitride, 2 Conductor Level(s); Purchased Thick Film on Alumina, 5 Conductor Level(s)

**Assembly Information: See Note 1/**

**Assembly Flows:** 12-0902

**Substrate Attach:** Nonconductive Epoxy, Solder

**Element Attach:** Conductive Epoxy, Solder, Nonconductive Epoxy, Eutectic

**Add-on Elements:** Unpackaged Die, Chip Resistors, Chip Capacitors

**Wire Bonding:** Gold, Aluminum

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Peripheral Leads, Seam Weld, 3.58 Inch Seal Perimeter, 16 Leads, Gold Lead Finish, Getter Qualified; Metal Package, TO can, Projection Weld, 1.65 Inch Seal Perimeter, 12 Leads, Gold Lead Finish, Getter Qualified; Metal Package, TO can, Projection Weld, 6.00 Inch Seal Perimeter, 12 Leads, Nickel Lead Finish, Getter Qualified; Ceramic Package, Dual-in-line, Seam Weld, 2.57 Inch Seal Perimeter, 14 Leads, Gold Lead Finish; Ceramic Package, Leadless Chip Carrier, Seam Weld, 1.62 Inch Seal Perimeter, 28 Leads, Solder Lead Finish; Ceramic Package, Single-in-line, Seam Weld, 2.90 Inch Seal Perimeter, 10 Leads, Gold Lead Finish; Copper Package, Single-in-line, Seam Weld, 4.90 Inch Seal Perimeter, 17 Leads, Nickel Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**API Technologies RF/Microwave & Microelectronics (CAGE Code: 50507)**

400 Nickerson Road, Marlborough, MA 01752, US

**Company Contact:** Mr. Gregory Madden, Phone: 508-251-6429, Fax: , E-mail: Gregory.Madden@apitech.com

**DSCC Contact:** Mr. Edward Raybould, Phone: 614-692-0582, Fax: 614-692-6942, E-mail: vqh.esr@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Data Converters, Track and Hold Amp

**Qualification Letters:** EQ(EQM-88-0709), EQ(EQC-91-235), EQ(EQC-91-894), EQ(EQC-92-062), EQ(EQC-93-162), EQ(EQC-94-008), ELS(ELSH-95-0269), VQ(VQH-06-010485)

**Class Level Information: See Note 6/**

Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Ceramic Co-fire

**Assembly Information: See Note 1/**

**Assembly Flows:** FC-25

**Substrate Attach:** Nonconductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Eutectic

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Chip Resistors

**Wire Bonding:** Gold

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Ceramic Package, Dual-in-line, Seam Weld, 7.48 Inch Seal Perimeter, 62 Leads, Gold/Solder Lead Finish; Ceramic Package, Leadless Chip Carrier, Solder Seal, 1.13 Inch Seal Perimeter, 22 Leads, Solder Lead Finish; Ceramic Package, Quad Flat Pack, Seam Weld, 6.20 Inch Seal Perimeter, 136 Leads, Gold Lead Finish



Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Avago Technologies (CAGE Code: 50434)**

No. 1 Yishun Avenue 7, Singapore, 768923

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**DSCC Contact:** Mr. Dan Miller, Phone: 614-692-2908, Fax: 614-692-6942, E-mail: vqh.dm@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Optocoupler

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**Qualification Letters:** EQ(EQM-87-2594), EQ(EQM-88-1265), EQ(EQC-90-0754), EQ(EQC-93-271), EQ(EQC-93-591), ELS(ELSH-95-271), VQ(VQH-97-047), VQ(VQH-00-0109), VQ(VQH-01-0164), VQ(VQH-02-000432), VQ(VQH-02-001278), VQ(VQH-04-006618), VQ(VQH-04-006839)

**Class Level Information:** See Note 6/

Class K, Class H, Class E

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Purchased Thick Film

**Assembly Information:** See Note 1/

**Assembly Flows:** ICPI-9001-3

**Substrate Attach:** Eutectic, Solder, Silver Glass

**Element Attach:** Eutectic, Silver Glass

**Add-on Elements:** Unpackaged Die

**Wire Bonding:** Gold, Aluminum

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** Ceramic Package, Dual-in-line, Solder Seal, 1.28 Inch Seal Perimeter, 16 Leads, Gold/Solder Lead Finish; Ceramic Package, Leadless Chip Carrier, Solder Seal, .92 Inch Seal Perimeter, 20 Leads, Solder Lead Finish; Ceramic Package, Peripheral Leads, Solder Seal, 1.32 Inch Seal Perimeter, 16 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**BI Technologies Corporation (CAGE Code: 73138)**

4200 Bonita Place, Fullerton, CA 92835-1053, US

**Company Contact:** Ms. Christine Martinez, Phone: 714-447-2340, Fax: 714-447-2300, E-mail: Christine.Martinez@ttelectronics.com

**DSCC Contact:** Mr. Christopher Hancock, Phone: 614-692-1309, Fax: 614-692-6942, E-mail: vqh.ch@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Voltage Regulator, Data Converters, Analog

**Qualification Letters:** EQ(EQC-89-071), EQ(EQC-91-718), EQ(EQC-92-382), EQ(EQC-92-383), VQH-97-0081, VQ(VQH-00-0095), VQ(VQH-10-020568), VQ(VQH-14-028022)

**Class Level Information: See Note 6/**

Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** 800-403-2

**Substrate Fabrication:** Thick Film on Alumina, 3 Conductor Level(s), Resistors

**Assembly Information: See Note 1/**

**Assembly Flows:** 800-403-03

**Substrate Attach:** Nonconductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Tabs, Chip Resistors

**Wire Bonding:** Gold

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Peripheral Leads, Seam Weld, 5.86 Inch Seal Perimeter, 61 Leads, Gold Lead Finish; Ceramic Package, Dual-in-line, Seam Weld, 6.87 Inch Seal Perimeter, 44 Leads, Gold Lead Finish; Ceramic Co-fire Package, Flatpack, Seam Weld, 1.04 Inch Seal Perimeter, 10 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**CMC Electronics Incorporated (CAGE Code: 90073)**

600 Dr. Frederik Philips Boulevard, Ville Saint Laurent, Quebec, H4M 2S9, Canada

**Company Contact:** Mr. Luc-Albert Laroche, Phone: 514-748-3000 x4136, Fax: 514-748-3100, E-mail: Luc-Albert.Laroche@cmcelectronics.ca

**DSCC Contact:** Mr. Christopher Hancock, Phone: 614-692-1309, Fax: 614-692-6942, E-mail: vqh.ch@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Voltage Regulator

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**Qualification Letters:** EQ(EQC-91-720), EQ(EQC-92-427), VQ(VQH-98-0133), VQ(VQH-04-005582)

**Class Level Information: See Note 6/**

Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** 411-146425-000

**Substrate Fabrication:** Thick Film on Alumina, 7 Conductor Level(s), Resistors

**Assembly Information: See Note 1/**

**Assembly Flows:** 411-146426-000

**Substrate Attach:** Nonconductive Epoxy, Conductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Eutectic

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Chip Resistors

**Wire Bonding:** Gold

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Axial Leads, Seam Weld, 3.61 Inch Seal Perimeter, 16 Leads, Gold Lead Finish; Metal Package, Bathtub, Seam Weld, 4.30 Inch Seal Perimeter, 24 Leads, Gold Lead Finish; Metal Package, Flatpack, Seam Weld, 1.56 Inch Seal Perimeter, 44 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Cobham Advanced Electronic Solutions Inc. (CAGE Code: 65628)**

9404 Chesapeake Drive, San Diego, CA 92123-1388, US

**Company Contact:** Mr. Ryan Blanchette, Phone: 858-505-3621, Fax: 858-560-0291, E-mail: Ryan.Blanchette@cobham.com

**DSCC Contact:** Mr. Richard Barker, Phone: 614-692-0596, Fax: 614-692-6942, E-mail: vqh.rb@dla.mil

**Quality Management (QM) Program:** TRB

**Periodic Inspection System:** Option 1

**Approved ISO 9000 System:** No

**Technologies:** Microwave Amplifier, Microwave Filter, Microwave Custom (IMAs)

**Qualification Letters:** ELS(ELSH-94-199), VQ(VQH-96-226), VQ(VQH-96-227), VQ(VQH-97-0180), VQ(VQH-97-0181), VQ(VQH-00-0104)

**Class Level Information:** See Note 6/

Class H, Class E

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Purchased Thin Film; Purchased Duriod; Purchased Polyimide/PWB Copper

**Assembly Information:** See Note 1/

**Assembly Flows:** 001775

**Substrate Attach:** Conductive Epoxy, Eutectic, Solder

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Solder

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Chip Resistors, Toroids, Coils, Thermcon, Inductors, Attenuators, IC Package

**Wire Bonding:** Gold, Copper, Ribbon

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** Metal Package, Peripheral Leads, Seam Weld, 4.00 Inch Seal Perimeter, 16 Leads, Gold Lead Finish; Aluminum/Stainless Steel Package, DC/Microwave Leads, Laser Weld, 12.50 Inch Seal Perimeter, 6 Leads; Aluminum/Stainless Steel Package, DC/Microwave Leads (Dual-Sided, Multi-Cavity), Laser Weld, 24.00 Inch Seal Perimeter, 4 Leads

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Crane Electronics Corporation (CAGE Code: 50821)**

5 South 6th Road Box 26-143, KEPZ, Kaohsiung, Taiwan, R.O.C 806

**Company Contact:** Mr. Stacy Irwin, Phone: 425-895-5038, Fax: 425-869-7402, E-mail: stacy.irwin@crane-eg.com

**DSCC Contact:** Mr. Richard Barker, Phone: 614-692-0596, Fax: 614-692-6942, E-mail: vqh.rb@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Option 1

**Approved ISO 9000 System:** No

**Technologies:** DC-DC Converter, EMI Filters

**Qualification Letters:** VQ(VQH-97-0266), VQ(VQH-99-0070), VQ(VQH-99-0134), VQ(VQH-99-0175), VQ(VQH-99-0200), VQ(VQH-01-0017), VQ(VQH-01-0060), VQ(VQH-02-001187), VQ(VQH-03-004414), VQ(VQH-04-006128), VQ(VQH-04-006855), VQ(VQH-05-008873), VQ(VQH-06-010206), VQ(VQH-06-011675), VQ(VQH-07-012130), VQ(VQH-07-012468), VQ(VQH-10-019428), VQ(VQH-10-019429), VQ(VQH-10-020020), VQ(VQH-11-021213), VQ(VQH-11-021614), VQ(VQH-11-021809), VQ(VQH-11-021810), VQ(VQH-11-021879), VQ(VQH-11-021880), VQ(VQH-14-028435)

**Class Level Information:** See Note 6/

Class H, Class E

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** QA-039

**Substrate Fabrication:** Thick Film on Alumina, 3 Conductor Level(s), Resistors; Thick Film on Beryllia, 3 Conductor Level(s), Resistors

**Assembly Information:** See Note 1/

**Assembly Flows:** QA-039

**Substrate Attach:** Solder, Nonconductive RTV, Conductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Solder, Eutectic

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Tantalum Capacitors, Tabs, Chip Resistors, Inductors, Toroids, Daughter Board

**Wire Bonding:** Gold, Aluminum, Copper

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** Metal Package, Axial Leads, Projection Weld, 5.14 Inch Seal Perimeter, 8 Leads, Gold Lead Finish; Metal Package, Peripheral Leads, Seam Weld, 8.00 Inch Seal Perimeter, 20 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Crane Electronics, Inc. (CAGE Code: 50821)**

10301 Willows Road, Redmond, WA 98052, US

**Company Contact:** Mr. Stacy Irwin, Phone: 425-895-5038, Fax: 425-869-7402, E-mail: stacy.irwin@crane-eg.com

**DSCC Contact:** Mr. Richard Barker, Phone: 614-692-0596, Fax: 614-692-6942, E-mail: vqh.rb@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Linear Amplifier, Signal Processor, Data Converters, DC/DC Converters, Analog, Digital, EMI Filters

**Qualification Letters:** EQ(EQM-87-2838), EQ(EQM-89-0439), EQ(EQC-92-174), EQ(EQC-92-300), EQ(EQC-93-031), EQ(EQC-93-056), EQ(EQC-93-196), EQ(EQC-93-221), EQ(EQC-93-280), EQ(EQC-93-550), EQC-93-624, EQ(EQM-94-043), EQ(EQM-94-0111), ELS(ELSH-94-0297), ELS(ELSH-94-0336), ELS(ELSH-94-0364), ELS(ELSH-95-0036), ELS(ELSH-95-0375), ELS(ELSH-96-0095), ELS(ELSH-96-0139), VQ(VQH-96-0214), VQ(VQH-98-0253), VQ(VQH-99-0013), VQ(VQH-00-0131), VQ(VQH-00-0188), VQ(VQH-03-003336), VQ(VQH-03-003760), VQ(VQH-04-006128), VQ(VQH-05-007236 AMENDED), VQ(VQH-05-008263), VQ(VQH-05-008516), VQ(VQH-05-008820), VQ(VQH-07-012129), VQ(VQH-07-012467), VQ(VQH-07-013397), VQ(VQH-13-026724), VQ(VQH-14-028435)

**Class Level Information: See Note 6/**

Class K, Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** QA-039

**Substrate Fabrication:** Thick Film on Alumina, 3 Conductor Level(s), Resistors; Thick Film on Beryllia, 3 Conductor Level(s), Resistors; Thick Film on Beryllia, 1 Conductor Level(s); Purchased Direct Bonded Copper

**Assembly Information: See Note 1/**

**Assembly Flows:** QA-039

**Substrate Attach:** Solder, Nonconductive Epoxy, Conductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Solder, Eutectic, RTV

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Tantalum Capacitors, Tabs, Chip Resistors, Inductors, Toroids, Daughter Board

**Wire Bonding:** Gold, Aluminum, Copper

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Axial Leads, Projection Weld, 4.26 Inch Seal Perimeter, 8 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 4.00 Inch Seal Perimeter, 32 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 8.75 Inch Seal Perimeter, 12 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Axial Leads, Seam Weld, 6.40 Inch Seal Perimeter, 5 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Axial Leads, Seam Weld, 6.00 Inch Seal Perimeter, 38 Leads, Gold/Solder Lead Finish, Getter Qualified

**Data Device Corporation (CAGE Code: 19645)**

105 Wilbur Place, Bohemia, NY 11716-2482, US

**Company Contact:** Mr. John Young, Phone: 631-567-5600 x7246, Fax: 631-244-8252, E-mail: young@ddc-web.com

**DSCC Contact:** Mr. Joseph Buben II, Phone: 614-692-0592, Fax: 614-692-6942, E-mail: vqh.jbu@dla.mil

**Quality Management (QM) Program:** TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** 1553 Bus, Data Converters, Power

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**Bohemia Line**

**Qualification Letters:** EQ(EQC-90-220), EQ(EQC-90-657), EQ(EQC-91-104), EQ(EQC-91-306), EQ(EQC-91-308), EQ(EQC-91-386), EQ(EQC-91-606), EQ(EQC-91-667), EQ(EQC-93-055), EQ(EQC-93-199), EQ(EQC-93-599), EQ(EQC-93-625), ELS(ELSH-94-0327), ELS(ELSH-94-0392), ELS(ELSH-94-0399), ELS(ELSH-95-0140), ELS(ELSH-95-0266), VQ(VQH-96-0203), VQ(VQH-98-0101), VQ(VQH-99-0033), VQ(VQH-99-0129), VQ(VQH-99-0222), VQ(VQH-02-0969), VQ(VQH-03-3982), VQ(VQH-04-5821), VQ(VQH-04-6876), VQ(VQH-06-010110), VQ(VQH-07-013396), VQ(VQH-10-019748)

**Class Level Information: See Note 6/**

Class K, Class H, Class D, Class G, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** 41638, 41639, 45552

**Substrate Fabrication:** Thick Film on Alumina, 4 Conductor Level(s), Resistors; Thin Film on Alumina, 1 Conductor Level(s); Thick Film on Beryllia, 1 Conductor Level(s), Resistors

**Assembly Information: See Note 1/**

**Assembly Flows:** 41634, 41635, 45552

**Substrate Attach:** Nonconductive Epoxy, Solder, Conductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Solder, Eutectic

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Tabs, Transformers, Chip Resistors, Tantalum Capacitors, Ceramic Capacitors

**Wire Bonding:** Gold, Aluminum, Copper/Tin Solder

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Peripheral Leads, Seam Weld, 8.80 Inch Seal Perimeter, 16 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Axial Leads, Seam Weld, 10.26 Inch Seal Perimeter, 94 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 7.58 Inch Seal Perimeter, 82 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, Axial Leads, Seam Weld, 7.34 Inch Seal Perimeter, 78 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, Peripheral Leads, Seam Weld, 7.34 Inch Seal Perimeter, 78 Leads, Gold Lead Finish, Getter Qualified; Ceramic Co-fire Package, Axial Leads, Seam Weld, 5.80 Inch Seal Perimeter, 70 Leads, Gold Lead Finish, Getter Qualified; Ceramic Co-fire Package, Peripheral Leads, Seam Weld, 5.80 Inch Seal Perimeter, 70 Leads, Gold Lead Finish, Getter Qualified; Ceramic Co-fire Package, Peripheral Leads, Seam Weld, 4.00 Inch Seal Perimeter, 81 Leads, Gold Lead Finish, Getter Qualified; Ceramic Co-fire Package, Axial Leads, Seam Weld, 4.00 Inch Seal Perimeter, 81 Leads, Gold Lead Finish, Getter Qualified; Ceramic Co-fire Package, J-Leads, Solder Seal, 2.12 Inch Seal Perimeter, 40 Leads, Gold Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Data Device Corporation (CAGE Code: 19645)**

105 Wilbur Place, Bohemia, NY 11716-2482, US

**Company Contact:** Mr. John Young, Phone: 631-567-5600 x7246, Fax: 631-244-8252, E-mail: young@ddc-web.com

**DSCC Contact:** Mr. Joseph Buben II, Phone: 614-692-0592, Fax: 614-692-6942, E-mail: vqh.jbu@dla.mil

**Quality Management (QM) Program:** TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** 1553 Bus, Data Converters, Power

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**sub: API Technologies Corp. RF2M UK (CAGE: U4388)**

**Qualification Letters:** EQ(EQC-91-835), EQ(EQC-92-084), EQ(EQC-93-139), ELS(ELSH-96-0054), ELS(ELSH-96-0161), VQ(VQH-98-0227), VQ(VQH-99-0192), VQ(VQH-99-0196), VQ(VQH-04-006510), VQ(VQH-04-007022), VQ(VQH-04-007023), VQ(VQH-05-008727), VQ(VQH-05-008978), VQ(VQH-06-010730), VQ(VQH-06-011795), VQ(VQH-09-017847), VQ(VQH-10-020173), VQ(VQH-10-020296), VQ(VQH-13-025883), VQ(VQH-14-028390)

**Class Level Information: See Note 6/**

Class K, Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** FCES 6301:15

**Substrate Fabrication:** Purchased Ceramic Co-fire; Thick Film on Alumina, 4 Conductor Level(s), Resistors; Purchased Direct Bonded Copper on Beryllia

**Assembly Information: See Note 1/**

**Assembly Flows:** FCES 6301:15

**Substrate Attach:** Conductive Epoxy, Solder, Nonconductive Epoxy

**Element Attach:** Conductive Epoxy, Eutectic, Nonconductive Epoxy

**Add-on Elements:** Chip Capacitors, Ceramic Tabs, Unpackaged Die, Transformers, Chip Resistors

**Wire Bonding:** Aluminum, Gold, Aluminum Ribbon

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Axial Leads, Projection Weld, 4.37 Inch Seal Perimeter, 24 Leads, Gold/Solder Lead Finish; Ceramic Co-fire Package, Dual-in-line, Seam Weld, 2.53 Inch Seal Perimeter, 24 Leads, Gold Lead Finish; Ceramic Package, Pin Grid Array, Seam Weld, 5.00 Inch Seal Perimeter, 101 Leads, Gold Lead Finish; Metal Package, TO can, Projection Weld, 1.13 Inch Seal Perimeter, 10 Leads, Gold/Solder Lead Finish; Ceramic Package, Dual-in-line, Seam Weld, 5.38 Inch Seal Perimeter, 32 Leads, Gold Lead Finish; Metal Package, Peripheral Leads, Seam Weld, 5.30 Inch Seal Perimeter, 36 Leads, Gold/Solder Lead Finish; Metal Package, Axial Leads, Seam Weld, 5.30 Inch Seal Perimeter, 36 Leads, Gold/Solder Lead Finish; Ceramic Package, Quad Flat Pack, Seam Weld, 3.48 Inch Seal Perimeter, 68 Leads, Gold Lead Finish



Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**International Rectifier Aerospace & Defense (CA) (CAGE Code: 52467)**

2520 Junction Avenue, San Jose, CA 95134-1902, US

**Company Contact:** Mr. Granville 'Bo' Rains, Phone: 408-434-5086, Fax: 408-434-5220, E-mail: grains1@irf.com

**DSCC Contact:** Ms. Jonnie Schneider, Phone: 614-692-0585, Fax: 614-692-6942, E-mail: vqh.jms@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** DC/DC Converters

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**Advanced Semiconductor Engrg Inc, Nantou Branch**

**Qualification Letters:** VQ(VQH-02-1624), VQ(VQH-05-009379)

**Class Level Information:** See Note 6/

Class H, Class E

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** N/A

**Assembly Information:** See Note 1/

**Assembly Flows:** 8002-0044

**Substrate Attach:** Conductive Epoxy, Nonconductive Epoxy, Solder

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Solder

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Tantalum Capacitors, Tabs, Chip Resistors, Transformers

**Wire Bonding:** Gold, Aluminum, Copper

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** Metal Package, Axial Leads, Seam Weld, 6.58 Inch Seal Perimeter, 10 Leads, Gold/Solder Lead Finish

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**Santa Clara Facility**

**Qualification Letters:** EQ(EQC-89-065), EQ(EQC-90-652), EQ(EQC-92-103), EQ(EQC-93-204), EQ(EQC-93-403), EQ(EQC-93-553), EQ(EQC-93-658), ELS(ELSH-94-0173), ELS(ELSH-94-0211), ELS(ELSH-94-0212), ELS(ELSH-94-0272), ELS(ELSH-94-0482), ELS(ELSH-94-0483), VQ(VQH-98-0100), VQ(VQH-98-0231), VQ(VQH-03-003517), VQ(VQH-05-9326), VQ(VQH-06-011051), VQ(VQH-07-013935), VQ(VQH-08-015552), VQ(VQH-12-023788), VQ(VQH-13-026800), VQ(VQH-14-027466), VQ(VQH-14-027974)

**Class Level Information:** See Note 6/

Class K, Class H, Class E

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** 8002-0044

**Substrate Fabrication:** Thick Film on Alumina, 5 Conductor Level(s), Resistors; Thick Film on Beryllia, 4 Conductor Level(s), Resistors; Purchased Direct Bonded Copper

**Assembly Information:** See Note 1/

**Assembly Flows:** 8002-0044

**Substrate Attach:** Conductive Epoxy, Nonconductive Epoxy, Solder

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Solder, RTV, Elastomer

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Tantalum Capacitors, Tabs, Chip Resistors, Transformers, Inductors, Wires, Terminals

**Wire Bonding:** Gold, Aluminum, Copper

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** Ceramic Package, Dual-in-line, Seam Weld, 3.69 Inch Seal Perimeter, 24 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Axial Leads, Seam Weld, 6.58 Inch Seal Perimeter, 10 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 10.10 Inch Seal Perimeter, 58 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 8.00 Inch Seal Perimeter, 12 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 11.00 Inch Seal Perimeter, 13 Leads, Gold/Solder Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**International Rectifier Aerospace & Defense (MA) (CAGE Code: 69210)**

205 Crawford Street, Leominster, MA 01453-2353, US

**Company Contact:** Ms. Cora Gustason, Phone: 978-466-5532, Fax: 978-537-4246, E-mail: cgustas1@irf.com

**DSCC Contact:** Ms. Jacqueline Cunningham, Phone: 614-692-0584, Fax: 614-692-6942, E-mail: vqh.jc@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Voltage Regulator, Power

**Qualification Letters:** EQ(EQC-91-408), EQ(EQC-91-807), EQ(EQC-91-838), EQ(EQM-94-0029), ELS(ELSH-94-0388), VQ(VQH-98-0014), VQ(VQH-01-0034), VQ(VQH-03-003838), VQ(VQH-08-016688), VQ(VQH-10-019960), VQ(VQH-10-020180), VQ(VQH-11-022643), VQ(VQH-12-024352), VQ(VQH-13-026659), VQ(VQH-13-026696)

**Class Level Information: See Note 6/**

Class K, Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** D050015G

**Substrate Fabrication:** Thick Film on Alumina, 3 Conductor Level(s), Resistors; Thick Film on Beryllia, 3 Conductor Level(s), Resistors

**Assembly Information: See Note 1/**

**Assembly Flows:** D050015G

**Substrate Attach:** Solder, Nonconductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Solder

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Tabs, Chip Resistors, Encapsulated Hybrid

**Wire Bonding:** Gold, Aluminum

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Peripheral Leads, Seam Weld, 2.47 Inch Seal Perimeter, 8 Leads, Solder Lead Finish; Metal Package, Peripheral Leads, Seam Weld, 8.80 Inch Seal Perimeter, 43 Leads, Gold Lead Finish; Metal Package, Axial Leads, Seam Weld, 4.08 Inch Seal Perimeter, 24 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, Peripheral Leads, Seam Weld, 2.14 Inch Seal Perimeter, 19 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**L-3 Communications Cincinnati Electronics (CAGE Code: 80045)**

7500 Innovation Way, Mason, OH 45040-9699, US

**Company Contact:** Ms. Jennifer Douglas, Phone: 513-573-6156, Fax: 513-573-6290, E-mail: Jennifer.Douglas@L-3Com.com

**DSCC Contact:** Mr. Richard Barker, Phone: 614-692-0596, Fax: 614-692-6942, E-mail: vqh.rb@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Option 1

**Approved ISO 9000 System:** No

**Technologies:** Custom, Analog, Amplifier, Linear

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**Qualification Letters:** VQ(VQH-98-0195), VQ(VQH-00-0167)

**Class Level Information:** See Note 6/

Class D

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** 637140

**Substrate Fabrication:** Thick Film on Alumina, 7 Conductor Level(s)

**Assembly Information:** See Note 1/

**Assembly Flows:** 637143

**Substrate Attach:** Nonconductive Epoxy

**Element Attach:** Conductive Epoxy

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Chip Resistors

**Wire Bonding:** Gold

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** Metal Package, Radial Leads, Laser Weld, 8.00 Inch Seal Perimeter, 69 Leads, Gold Lead Finish

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**Qualification Letters:** EQ(EQC-93-113), EQC-93-197, ELS(ELSH-94-417), VQ(VQH-01-0034), VQ(VQH-10-020213)

**Class Level Information:** See Note 6/

Class K, Class H, Class E

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** 637140

**Substrate Fabrication:** Thick Film on Alumina, 6 Conductor Level(s)

**Assembly Information:** See Note 1/

**Assembly Flows:** 637143

**Substrate Attach:** Nonconductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Chip Resistors

**Wire Bonding:** Gold

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** Metal Package, Axial Leads, Seam Weld, 3.48 Inch Seal Perimeter, 18 Leads, Gold Lead Finish; Metal Package, Peripheral Leads, Seam Weld, 3.58 Inch Seal Perimeter, 20 Leads, Gold Lead Finish; Metal Package, Axial Leads, Seam Weld, 5.20 Inch Seal Perimeter, 30 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Lockheed Martin Missiles and Fire Control (CAGE Code: 04939)**

5600 Sand Lake Road MP189, Orlando, FL 32819-8907, US

**Company Contact:** Ms. Kristina Lydiard, Phone: 407-356-5060, Fax: 407-356-6808, E-mail: kristina.lydiard@lmco.com

**DSCC Contact:** Ms. Jonnie Schneider, Phone: 614-692-0585, Fax: 614-692-6942, E-mail: vqh.jms@dla.mil

**Quality Management (QM) Program:** TRB

**Periodic Inspection System:** Option 1

**Approved ISO 9000 System:** No

**Technologies:** Digital, Analog

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**Qualification Letters:** EQ(EQC-91-402), EQ(EQC-91-764), EQ(EQC-92-112), EQ(EQC-92-312), EQ(EQC-92-412), VQ(VQH-99-0164), VQ(VQH-10-020356)

**Class Level Information: See Note 6/**

Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Purchased Thick Film

**Assembly Information: See Note 1/**

**Assembly Flows:** 72301772

**Substrate Attach:** Nonconductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Eutectic

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Tantalum Capacitors, Chip Resistors, Inductors

**Wire Bonding:** Gold, Aluminum

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Ceramic Package, Leadless Chip Carrier, Solder Seal, 3.80 Inch Seal Perimeter, 68 Leads, Gold Lead Finish; Ceramic Package, Dual-in-line, Solder Seal, 2.88 Inch Seal Perimeter, 18 Leads, Gold/Solder Lead Finish; Metal Package, Platform, Projection Weld, 5.76 Inch Seal Perimeter, 44 Leads, Gold Lead Finish; Metal Package, Axial Leads, Seam Weld, 11.80 Inch Seal Perimeter, 140 Leads, Gold Lead Finish

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**Qualification Letters:** VQ(VQH-12-024704)

**Class Level Information: See Note 6/**

Class D

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Purchased Thick Film

**Assembly Information: See Note 1/**

**Assembly Flows:** 861 Process Flow

**Substrate Attach:** Solder

**Element Attach:** Conductive Epoxy

**Add-on Elements:** Unpackaged Die, Chip Capacitor

**Wire Bonding:** Gold

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Axial Leads, Projection Weld, 1.88 Inch Seal Perimeter, 16 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**M.S. Kennedy Corporation (CAGE Code: 51651)**

4707 Dey Road, Liverpool, NY 13088-3510, US

**Company Contact:** Mr. Daniel Miller, Phone: 315-701-6751, Fax: 315-701-6752, E-mail: d.miller@mskennedy.com

**DSCC Contact:** Ms. Binh Tonnu, Phone: 614-692-0586, Fax: 614-692-6942, E-mail: vqh.bt@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** High Power Amplifiers, Amplifiers, PWB H-Bridge, Custom Hybrids/MCMs, Voltage Regulator, Switching Regulator, RAD HARD Hybrids, Motor Controllers, Linear Regulators, DC/DC Converters, Filters, Video Amplifiers

**Qualification Letters:** EQ(EQC-90-451), EQ(EQC-90-507), EQ(EQC-92-417), EQ(EQC-93-141), EQ(EQC-93-242), EQ(EQC-93-346), EQ(EQC-93-488), EQ(EQC-93-554), EQ(EQC-93-682), EQ(EQC-93-687), EQ(EQM-94-084), EQ(EQM-94-093), ELS(ELSH-94-0400), ELS(ELSH-94-0401), ELS(ELSH-94-0402), ELS(ELSH-94-0470), ELS(ELSH-95-0020), ELS(ELSH-95-0216), ELS(ELSH-95-0304), ELS(ELSH-96-0073), ELS(ELSH-96-0086), VQ(VQH-96-0206), VQ(VQH-97-0046), VQ(VQH-97-0073), VQ(VQH-97-0089), VQ(VQH-97-0223), VQ(VQH-97-0228), VQ(VQH-97-0238), VQ(VQH-97-0243), VQ(VQH-98-0246), VQ(VQH-99-0145), VQ(VQH-00-0023), VQ(VQH-00-0242), VQ(VQH-01-0065), VQ(VQH-01-0075), VQ(VQH-02-000095), VQ(VQH-03-002841), VQ(VQH-03-003922), VQ(VQH-03-004192), VQ(VQH-03-004194), VQ(VQH-04-005084), VQ(VQH-04-005148), VQ(VQH-04-005646), VQ(VQH-04-006786), VQ(VQH-04-006941), VQ(VQH-04-007061), VQ(VQH-04-007098), VQ(VQH-05-008546), VQ(VQH-05-008816), VQ(VQH-05-008994), VQ(VQH-05-008995), VQ(VQH-06-009631), VQ(VQH-06-009683), VQ(VQH-06-009742), VQ(VQH-06-010016), VQ(VQH-06-010082), VQ(VQH-06-010086), VQ(VQH-06-010359), VQ(VQH-06-010509), VQ(VQH-06-010846), VQ(VQH-06-011516), VQ(VQH-07-012278), VQ(VQH-07-012548), VQ(VQH-07-013658), VQ(VQH-08-014579), VQ(VQH-08-014909), VQ(VQH-09-016693), VQ(VQH-09-018310), VQ(VQH-09-018313), VQ(VQH-09-018466), VQ(VQH-09-018978), VQ(VQH-10-021073), VQ(VQH-11-022826), VQ(VQH-11-022827), VQ(VQH-11-022828), VQ(VQH-11-023107), VQ(VQH-11-023174), VQ(VQH-11-023234), VQ(VQH-12-024146), VQ(VQH-13-025668), VQ(VQH-13-026264), VQ(VQH-14-027599), VQ(VQH-14-027663)

**Class Level Information:** See Note 6/

Class K, Class H, Class G, Class E

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** 2422-1563

**Substrate Fabrication:** Thick Film on Alumina, 2 Conductor Level(s), Resistors; Thick Film on Alumina, 6 Conductor Level(s); Purchased Alumina/Copper; Thick Film on Beryllia, 3 Conductor Level(s), Resistors; Thick Film on Beryllia, 1 Conductor Level(s); Purchased Alumina

**Assembly Information:** See Note 1/

**Assembly Flows:** 2422-1518

**Substrate Attach:** Conductive Epoxy, Nonconductive Epoxy, Solder

**Element Attach:** Solder, Conductive Epoxy, Nonconductive Epoxy, Eutectic

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Tabs, Chip Resistors, Inductors, Bonding Block, Daughter Board, Crystal, Ceramic Posts

**Wire Bonding:** Gold, Aluminum

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** Metal Package, TO Can, Projection Weld, 3.14 Inch Seal Perimeter, 12 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Platform, Projection Weld, 2.60 Inch Seal Perimeter, 14 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Axial Leads, Seam Weld, 5.00 Inch Seal Perimeter, 44 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 6.95 Inch Seal Perimeter, 82 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 6.00 Inch Seal Perimeter, 12 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, Brazed Leads, Solder Seal, 2.06 Inch Seal Perimeter, 28 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Surface Mount, Seam Weld, 2.15 Inch Seal Perimeter, 3 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, Peripheral Leads, Seam Weld, 4.79 Inch Seal Perimeter, 10 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, Flatpack, Seam Weld, 2.38 Inch Seal Perimeter, 10 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Flatpack, Seam Weld, 5.98 Inch Seal Perimeter, 196 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Flatpack, Solder Seal, 1.33 Inch Seal Perimeter, 14 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Bathtub, Seam Weld, 2.45 Inch Seal Perimeter, 5 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, LCC, Solder Seal, 1.40 Inch Seal Perimeter, 20 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, LCC, Seam Weld, 2.16 Inch Seal Perimeter, 3 Leads, Gold Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Micropac Industries, Incorporated (CAGE Code: 31757)**

905 East Walnut Street, Garland, TX 75040-6696, US

**Company Contact:** Mr. Cecil Miller, Phone: 972-272-3571, Fax: 972-494-2281, E-mail: cmiller@micropac.com

**DSCC Contact:** Mr. Dan Miller, Phone: 614-692-2908, Fax: 614-692-6942, E-mail: vqh.dm@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Custom, Power, Optocouplers

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**Inmobiliaria San Jose De Co. Plant**

**Qualification Letters:** VQ(VQH-04-005466), VQ(VQH-06-010381), VQ(VQH-06-011928)

**Class Level Information:** See Note 6/

Class H, Class E

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** N/A

**Assembly Information:** See Note 1/

**Assembly Flows:** 90138

**Substrate Attach:** N/A

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy

**Add-on Elements:** Unpackaged Die, Chip Resistors, Spacer

**Wire Bonding:** Gold

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** N/A

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**Micropac Custom Line, Garland TX**

**Qualification Letters:** EQ(EQC-91-178), EQ(EQC-91-647), EQ(EQC-92-183), EQ(EQC-92-258), VQ(VQH-04-006232), VQ(VQH-05-008704), VQ(VQH-05-009200), VQ(VQH-05-009466), VQ(VQH-06-011928), VQ(VQH-07-012661), VQ(VQH-07-013773)

**Class Level Information:** See Note 6/

Class K, Class H, Class E

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** 90138

**Substrate Fabrication:** Thick Film on Alumina, 5 Conductor Level(s), Resistors

**Assembly Information:** See Note 1/

**Assembly Flows:** 90138

**Substrate Attach:** Nonconductive Epoxy, Solder

**Element Attach:** Eutectic, Conductive Epoxy, Nonconductive Epoxy

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Chip Resistors

**Wire Bonding:** Gold

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** Metal Package, Axial Leads, Seam Weld, 5.00 Inch Seal Perimeter, 28 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 5.00 Inch Seal Perimeter, 46 Leads, Gold/Solder Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Micropac Industries, Incorporated (CAGE Code: 31757)**

905 East Walnut Street, Garland, TX 75040-6696, US

**Company Contact:** Mr. Cecil Miller, Phone: 972-272-3571, Fax: 972-494-2281, E-mail: cmiller@micropac.com

**DSCC Contact:** Mr. Dan Miller, Phone: 614-692-2908, Fax: 614-692-6942, E-mail: vqh.dm@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Custom, Power, Optocouplers

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**Micropac Opto Line, Garland TX**

**Qualification Letters:** EQ(EQC-90-624), EQ(EQC-91-188), EQ(EQC-91-466), EQ(EQC-92-120), ELS(ELSH-95-0057), ELS(ELSH-95-0444), VQ(VQH-04-006232), VQ(VQH-05-008721), VQ(VQH-12-025123), VQ(VQH-15-028695)

**Class Level Information:** See Note 6/

Class K, Class H, Class E

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** 90138

**Substrate Fabrication:** Thick Film on Alumina, 2 Conductor Level(s), Resistors; Thick Film on Alumina, 1 Conductor Level(s)

**Assembly Information:** See Note 1/

**Assembly Flows:** 90138

**Substrate Attach:** Conductive Epoxy, Nonconductive Epoxy

**Element Attach:** Eutectic, Conductive Epoxy

**Add-on Elements:** Unpackaged Die, Chip Resistors

**Wire Bonding:** Gold

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** Ceramic Package, Dual-in-line, Solder Seal, 1.89 Inch Seal Perimeter, 16 Leads, Gold/Solder Lead Finish, Getter Qualified; Ceramic Package, Leadless Chip Carrier, Solder Seal, 1.60 Inch Seal Perimeter, 24 Leads, Solder Lead Finish, Getter Qualified; Metal Package, TO Can (dual base), Projection Weld, .54 Inch Seal Perimeter, 7 Leads, Gold/Solder Lead Finish, Getter Qualified; Ceramic Package, Dual-in-line, Seam Weld, 1.33 Inch Seal Perimeter, 8 Leads, Gold/Solder Lead Finish, Getter Qualified

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**Micropac Power Line, Garland TX**

**Qualification Letters:** EQ(EQC-90-625), EQ(EQC-91-328), EQ(EQC-91-338), EQ(EQC-92-183), EQ(EQC-92-258), ELS(ELSH-94-0496), VQ(VQH-04-006232), VQ(VQH-05-007911), VQ(VQH-05-009200), VQ(VQH-06-011765), VQ(VQH-07-013121), VQ(VQH-08-015994), VQ(VQH-12-025067), VQ(VQH-14-027805)

**Class Level Information:** See Note 6/

Class K, Class H, Class E

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** 90138

**Substrate Fabrication:** Thick Film on Alumina, 1 Conductor Level(s), Resistors; Thick Film on Beryllia, 2 Conductor Level(s), Resistors

**Assembly Information:** See Note 1/

**Assembly Flows:** 90138

**Substrate Attach:** Nonconductive Epoxy, Solder

**Element Attach:** Conductive Epoxy, Solder, Eutectic

**Add-on Elements:** Unpackaged Die, Chip Capacitors

**Wire Bonding:** Gold, Aluminum

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** Metal Package, TO Can, Projection Weld, 2.27 Inch Seal Perimeter, 8 Leads, Gold/Solder Lead Finish, Getter Qualified; Ceramic Package, Dual-in-line, Seam Weld, 1.36 Inch Seal Perimeter, 8 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Micro-Precision Technologies, Inc. (CAGE Code: 0F962)**

10 Manor Parkway, Salem, NH 03079-2841, US

**Company Contact:** Dr. Etang Chen, Phone: 603-893-7600, Fax: 603-893-9110, E-mail: ec@micropt.com

**DSCC Contact:** Ms. Binh Tonnu, Phone: 614-692-0586, Fax: 614-692-6942, E-mail: vqh.bt@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Option 1

**Approved ISO 9000 System:** Yes

**Technologies:** Linear, Digital, Analog

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**Qualification Letters:** VQ(VQH-00-0004), VQ(VQH-10-019928)

**Class Level Information: See Note 6/**

Class H, Class G, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** CP9146-Screening Rev. -

**Substrate Fabrication:** Thick Film on Alumina, 3 Conductor Level(s), Resistors

**Assembly Information: See Note 1/**

**Assembly Flows:** CP9146Q-Assembly Traveler Rev. -

**Substrate Attach:** Nonconductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Solder

**Add-on Elements:** Unpackaged Die, Chip Resistors, Chip Capacitors

**Wire Bonding:** Gold

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Peripheral Leads, Seam Weld, 6.32 Inch Seal Perimeter, 65 Leads, Gold Lead Finish



Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Microsemi HRG SUSP. DUE TO FACILITY MOVE (CAGE Code: 43611)**

6 Lake Street, Lawrence, MA 01841, US

**Company Contact:** Ms. Sue Powers, Phone: 978-620-2475, Fax: 978-774-0939, E-mail: spowers@microsemi.com

**DSCC Contact:** Mr. Christopher Hancock, Phone: 614-692-1309, Fax: 614-692-6942, E-mail: vqh.ch@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Option 2

**Approved ISO 9000 System:** No

**Technologies:** Solid State Switch

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**Qualification Letters:** VQ(VQH-12-024364), VQ(VQH-12-025103), VQ(VQH-13-027082)

**Class Level Information: See Note 6/**

Class K, Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** 7-458K

**Substrate Fabrication:** Thick Film on Alumina, 1 Conductor Level(s), Resistors; Purchased Copper on BeO, 1 Conductor Level(s)

**Assembly Information: See Note 1/**

**Assembly Flows:** T3-HPG-SC001

**Substrate Attach:** Solder, Nonconductive Epoxy

**Element Attach:** Conductive Epoxy, Eutectic, Solder, Nonconductive Epoxy

**Add-on Elements:** Daughter Board, Chip Capacitors, Tabs, Unpackaged Die, Chip Resistors, Inductors

**Wire Bonding:** Aluminum, Gold

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Flatpack, Seam Weld, 3.85 Inch Seal Perimeter, 8 Leads, Gold Lead Finish; Metal Package, Flatpack, Seam Weld, 3.64 Inch Seal Perimeter, 16 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Microsemi Power & Microelectronics Group (CAGE Code: 54230)**

3601 East University Drive, Phoenix, AZ 85034-7217, US

**Company Contact:** Ms. Usha Shah, Phone: 602-437-1520 x13225, Fax: 602-437-9120, E-mail: Usha.shah@microsemi.com

**DSCC Contact:** Ms. Jacqueline Cunningham, Phone: 614-692-0584, Fax: 614-692-6942, E-mail: vqh.jc@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Digital Memory

**Qualification Letters:** EQ(EQC-90-019), EQ(EQC-92-070), EQ(EQC-92-138), EQC-93-457, EQ(EQC-93-508), ELS(ELSH-94-0256), ELS(ELSH-95-0107), ELS(ELSH-95-0365), ELS(ELSH-96-0014), ELS(ELSH-96-0184), ELS(ELSH-96-0186), VQ(VQH-96-0210), VQ(VQH-96-0211), VQ(VQH-97-0016), VQ(VQH-97-0170), VQ(VQH-98-0172), VQ(VQH-99-0258), VQ(VQH-00-0079)

**Class Level Information: See Note 6/**

Class K, Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Purchased Thick Film; Purchased Ceramic Co-fire

**Assembly Information: See Note 1/**

**Assembly Flows:** 035A00001

**Substrate Attach:** Nonconductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Chip Resistors

**Wire Bonding:** Gold

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Ceramic Co-fire Package, Brazed Leads, Seam Weld, 5.36 Inch Seal Perimeter, 68 Leads, Gold/Solder Lead Finish, Getter Qualified; Ceramic Co-fire Package, Axial Leads, Seam Weld, 4.58 Inch Seal Perimeter, 66 Leads, Gold/Solder Lead Finish, Getter Qualified; Ceramic Package, Pin Grid Array, Seam Weld, 4.10 Inch Seal Perimeter, 66 Leads, Gold Lead Finish, Getter Qualified

**Amertron Inc. (Philippines)**

**Qualification Letters:** VQ(VQH-12-024754)

**Class Level Information: See Note 6/**

Class H

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Purchased Ceramic Co-fire

**Assembly Information: See Note 1/**

**Assembly Flows:** 035A00001

**Substrate Attach:** N/A

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy

**Add-on Elements:** Unpackaged Die, Chip Capacitors

**Wire Bonding:** N/A

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Ceramic Co-fire Package, Brazed Leads, Seam Weld, 3.32 Inch Seal Perimeter, 68 Leads, Gold/Solder Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

***Micross Components, Austin (CAGE Code: 0EU86)***

8701 Cross Park Drive, Austin, TX 78754-4566, US

**Company Contact:** Mr. Allen Wares, Phone: 512-339-1188 x7138, Fax: 512-339-6641, E-mail: Allen.Wares@micross.com

**DSCC Contact:** Mr. Joseph Buben II, Phone: 614-692-0592, Fax: 614-692-6942, E-mail: vqh.jbu@dla.mil

**Quality Management (QM) Program:** TRB

**Periodic Inspection System:** Option 1

**Approved ISO 9000 System:** No

**Technologies:** Memory

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**Micross Components, Austin**

**Qualification Letters:** VQ(VQH-99-0144), VQ(VQH-05-009274), VQ(VQH-05-009315), VQ(VQH-05-009388), VQ(VQH-05-009621), VQ(VQH-06-009807), VQ(VQH-06-010137), VQ(VQH-06-010562), VQ(VQH-06-010804), VQ(VQH-07-012340), (VQ(VQH-09-017567)

**Class Level Information:** See Note 6/

Class H, Class E

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** N/A

**Assembly Information:** See Note 1/

**Assembly Flows:** 2/ASI-H/512K32F1/A, 1595, 1648, AS85512K32P-SAD, S51232MA, R12832MA

**Substrate Attach:** N/A

**Element Attach:** Ag Cyanate Ester, Eutectic, Noncond. Cyanate Ester, Conductive Epoxy, Nonconductive Epoxy

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Chip Resistors

**Wire Bonding:** Gold, Aluminum

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** Ceramic Co-fire Package, Quad Flat Pack, Solder Seal, 1.76 Inch Seal Perimeter, 68 Leads, Gold Lead Finish; Ceramic Package, Dual-in-line, Solder Seal, 1.44 Inch Seal Perimeter, 14 Leads, Solder Lead Finish; Ceramic Co-fire Package, Pin Grid Array, Seam Weld, 4.06 Inch Seal Perimeter, 66 Leads, Gold/Solder Lead Finish; Ceramic Co-fire Package, Quad Flat Pack, Seam Weld, 3.34 Inch Seal Perimeter, 68 Leads, Gold/Solder Lead Finish; Ceramic Co-fire Package, Quad Flat Pack, Seam Weld, 5.60 Inch Seal Perimeter, 68 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Murata Power Solutions Inc. (Datel) (CAGE Code: 50721)**

11 Cabot Boulevard, Mansfield, MA 02048-1194, US

**Company Contact:** Mr. Gerald Mesolella, Phone: 508-964-5159, Fax: 508-339-6356, E-mail: gmesolella@murata.com

**DSCC Contact:** Mr. Edward Raybould, Phone: 614-692-0582, Fax: 614-692-6942, E-mail: vqh.esr@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Digital

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**Qualification Letters:** EQ(EQC-90-626), EQ(EQC-90-677), EQ(EQC-91-029), EQ(EQC-92-446), ELS(ELSH-95-0356), VQ(VQH-97-0084), VQ(VQH-98-0261), VQ(VQH-07-012296), VQ(VQH-10-019587), VQ(VQH-11-022867)

**Class Level Information: See Note 6/**

Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** D-4552

**Substrate Fabrication:** Thick Film on Alumina, 7 Conductor Level(s)

**Assembly Information: See Note 1/**

**Assembly Flows:** D-4552

**Substrate Attach:** Nonconductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Tantalum Capacitors, Chip Resistors

**Wire Bonding:** Gold

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Ceramic Package, Dual-in-line, Seam Weld, 7.24 Inch Seal Perimeter, 62 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Natel Carson City Operations (CAGE Code: 0ANM4)**

400 Hot Springs Road, Carson City, NV 89706-1609, US

**Company Contact:** Mrs. Kathy Cano, Phone: 775-883-0820, Fax: 775-883-0827, E-mail: kcano@natelems.com

**DSCC Contact:** Mr. Edward Raybould, Phone: 614-692-0582, Fax: 614-692-6942, E-mail: vqh.esr@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Active Delay Line, Linear, Custom Hybrid

**Qualification Letters:** EQ(EQC-91-859), EQ(EQM-94-0023), EQ(EQM-94-0102), VQ(VQH-04-006262), VQ(VQH-05-007828), VQ(VQH-06-010743), VQ(VQH-07-012497), VQ(VQH-08-015017), VQ(VQH-08-015553), VQ(VQH-09-016945), VQ(VQH-10-020918), VQ(VQH-14-027901)

**Class Level Information: See Note 6/**

Class K, Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** RN1005-002, 8111663

**Substrate Fabrication:** Thick Film on Alumina, 2 Conductor Level(s), Resistors; Thick Film on Beryllia, 1 Conductor Level(s); Thick Film on Ceramic, 7 Conductor Level(s), Resistors

**Assembly Information: See Note 1/**

**Assembly Flows:** RN1005-004

**Substrate Attach:** Nonconductive Epoxy, Conductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Solder, Eutectic

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Inductors, Chip Resistors, Tabs, Tantalum Capacitors, Quartz Crystal, Ceramic Stand Off, Daughter Board

**Wire Bonding:** Gold, Aluminum

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Platform, Projection Weld, 2.94 Inch Seal Perimeter, 16 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Axial Leads, Seam Weld, 6.32 Inch Seal Perimeter, 48 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Axial Leads, Seam Weld, 5.00 Inch Seal Perimeter, 56 Leads, Nickel Lead Finish, Getter Qualified; Ceramic Co-fire Package, Brazed Leads, Seam Weld, 2.47 Inch Seal Perimeter, 11 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Natel Engineering Company, Inc. (CAGE Code: 09059)**

9340 Owensmouth Avenue, Chatsworth, CA 91311-6915, US

**Company Contact:** Mr. Jay Klug, Phone: 818-734-6568, Fax: 818-734-6540, E-mail: jklug@natelengr.com

**DSCC Contact:** Ms. Jonnie Schneider, Phone: 614-692-0585, Fax: 614-692-6942, E-mail: vqh.jms@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Option 2

**Approved ISO 9000 System:** No

**Technologies:** Hybrid Microcircuits, Custom Hybrids, Multichip Modules

**Qualification Letters:** EQ(EQC-91-714), EQ(EQC-92-039), EQ(EQC-92-048), EQ(EQC-92-202), EQ(EQC-93-261), ELS(ELSH-95-0154), ELS(ELSH-95-0314), VQ(VQH-01-156), VQ(VQH-03-004107)

**Class Level Information: See Note 6/**

Class K, Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Purchased Direct Bonded Copper; Purchased Thick Film on Beryllia/Alumina, 1 Conductor Level(s)

**Assembly Information: See Note 1/**

**Assembly Flows:** NHPS-01.001, NPS-01.016

**Substrate Attach:** Nonconductive Epoxy, Conductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Eutectic

**Add-on Elements:** Ceramic Posts, Chip Capacitors, Chip Resistors, Daughter Board, Unpackaged Die

**Wire Bonding:** Gold, Aluminum

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Peripheral Leads, Seam Weld, 5.34 Inch Seal Perimeter, 36 Leads, Gold Lead Finish; Metal Package, Axial Leads, Seam Weld, 6.56 Inch Seal Perimeter, 40 Leads, Gold Lead Finish; Metal Package, Single-in-line, Seam Weld, 4.34 Inch Seal Perimeter, 14 Leads, Nickel Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Pantronix Corporation (CAGE Code: 2V289)**

2710 Lakeview Court, Fremont, CA 94538, US

**Company Contact:** Mr. Solomon Ching, Phone: 510-656-5898, Fax: 510-656-7779, E-mail: sching@pantronix.com

**DSCC Contact:** Ms. Binh Tonnu, Phone: 614-692-0586, Fax: 614-692-6942, E-mail: vqh.bt@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Option 1

**Approved ISO 9000 System:** No

**Technologies:** Custom, Digital, Analog

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**Qualification Letters:** VQ(VQH-06-010701)

**Class Level Information:** See Note 6/

Class D

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Purchased LTCC on Ceramic, 10 Conductor Level(s)

**Assembly Information:** See Note 1/

**Assembly Flows:** 710-023

**Substrate Attach:** N/A

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Eutectic, Silver Glass

**Add-on Elements:** Unpackaged Die, Chip Resistors, Chip Capacitors, Ceramic Posts

**Wire Bonding:** Gold, Aluminum

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** Ceramic Package, Quad Flat Pack, Seam Weld, 5.38 Inch Seal Perimeter, 270 Leads, Gold Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Precision Devices Incorporated (CAGE Code: 0S4G1)**

8840 N. Greenview Drive, Middleton, WI 53562, US

**Company Contact:** Mr. Chris Harden, Phone: 608-203-0230, Fax: 608-831-3343, E-mail: Chris\_H@pdixtal.com

**DSCC Contact:** Ms. Jonnie Schneider, Phone: 614-692-0585, Fax: 614-692-6942, E-mail: vqh.jms@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Option 2

**Approved ISO 9000 System:** No

**Technologies:** Crystal oscillator, Hybrid assemblies

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**Qualification Letters:** VQ(VQH-05-007968), VQ(VQH-12-024419)

**Class Level Information: See Note 6/**

Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Purchased FR4 printed circuit board, 2 Conductor Level(s)

**Assembly Information: See Note 1/**

**Assembly Flows:** CP 7.5.1.38-A, cp 7.5.1.40-A

**Substrate Attach:** Solder

**Element Attach:** Solder

**Add-on Elements:** surface mount (smd) caps, smd resistors, smd plastic active device, smd ceramic active device, metal canned crystals, smd ceramic crystals

**Wire Bonding:** N/A

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Dual-in-line, Projection Weld, 2.85 Inch Seal Perimeter, 14 Leads, Solder Lead Finish; Metal Package, Peripheral Leads, Seam Weld, 7.18 Inch Seal Perimeter, 24 Leads, Gold Lead Finish



Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Robins AFB (CAGE Code: 0RCH2)**

402 EMXSS/MXDEAD, 420 Richard Ray Blvd Ste 100, Robins AFB, GA 31098-1640, US

**Company Contact:** Ms. Kimberly Dockery, Phone: 478-926-9472, Fax: 478-926-9234, E-mail: Kimberly.Dockery@ROBINS.AF.MIL

**DSCC Contact:** Ms. Binh Tonnu, Phone: 614-692-0586, Fax: 614-692-6942, E-mail: vqh.bt@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Option 1

**Approved ISO 9000 System:** No

**Technologies:** I/Q Phase Detector, Digibus

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**Qualification Letters:** VQ(VQH-00-0107), VQ(VQH-07-012450), VQ(VQH-13-025669)

**Class Level Information: See Note 6/**

Class H, Class G, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Purchased Thick Film on Alumina, 4 Conductor Level(s)

**Assembly Information: See Note 1/**

**Assembly Flows:** PCD0200

**Substrate Attach:** Conductive Epoxy, Nonconductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Chip Resistors

**Wire Bonding:** Gold

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Flatpack, Seam Weld, 5.92 Inch Seal Perimeter, 68 Leads, Gold Lead Finish; Ceramic Package, Flatpack, Seam Weld, 4.02 Inch Seal Perimeter, 30 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Sensitron Semiconductor (CAGE Code: 13409)**

221 West Industry Court, Deer Park, NY 11729-4681, US

**Company Contact:** Ms. Suzanne Doyle, Phone: 631-586-7600 x451, Fax: 631-586-7652, E-mail: Suzanne.Doyle@rsm.com

**DSCC Contact:** Ms. Binh Tonnu, Phone: 614-692-0586, Fax: 614-692-6942, E-mail: vqh.bt@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Power, Transistors

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**Qualification Letters:** VQ(VQH-00-0119), VQ(VQH-00-0168), VQ(VQH-00-0169), VQ(VQH-03-002777)

**Class Level Information:** See Note 6/

Class H, Class E

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Purchased Aluminum Nitride

**Assembly Information:** See Note 1/

**Assembly Flows:** 7710-0582

**Substrate Attach:** Solder

**Element Attach:** Conductive Epoxy, Solder, Eutectic

**Add-on Elements:** Unpackaged Die, Chip Resistors

**Wire Bonding:** Gold, Aluminum

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** Metal Package, Axial Leads, Seam Weld, 4.00 Inch Seal Perimeter, 12 Leads, Gold Lead Finish; Metal Package, Solder Seal, 1.96 Inch Seal Perimeter; Metal Package, TO Can, Projection Weld, 1.13 Inch Seal Perimeter, 8 Leads, Gold Lead Finish

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**Qualification Letters:** N/A

**Class Level Information:** See Note 6/

Class D

**Substrate Fabrication Information:** See Note 1/

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Purchased Beryllia; Purchased Alumina

**Assembly Information:** See Note 1/

**Assembly Flows:** 7710-0582

**Substrate Attach:** Solder

**Element Attach:** Solder

**Add-on Elements:** Packaged FET, Chip Resistors, Chip Capacitors

**Wire Bonding:** Copper

**Package Information:** See Notes 1/ 2/ 3/

**Package Information:** Epoxy Package, Axial Leads, Epoxy Seal, 4.64 Inch Seal Perimeter, 16 Leads, Copper Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Solitron Devices, Incorporated (CAGE Code: 21845)**

3301 Electronics Way, West Palm Beach, FL 33407-4697, US

**Company Contact:** Mr. Michael Radulovich, Phone: 561-848-4311, Fax: 561-863-5946, E-mail: mradulovich@solitrondevices.com

**DSCC Contact:** Mr. Dan Miller, Phone: 614-692-2908, Fax: 614-692-6942, E-mail: vqh.dm@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Linear, Power, Voltage Regulator

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**Qualification Letters:** ELS(ELSH-94-0316), ELS(ELSH-94-0433), ELS(ELSH-95-0079), ELS(ELSH-95-0210), VQ(VQH-99-0180), VQ(VQH-99-0195), VQ(VQH-00-0125), VQ(VQH-03-003255), VQ(VQH-03-004107), VQ(VQH-05-007716), VQ(VQH-14-028224)

**Class Level Information: See Note 6/**

Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** H1043

**Substrate Fabrication:** Thick Film on Alumina, 1 Conductor Level(s), Resistors; Thick Film on Beryllia, 2 Conductor Level(s), Resistors; Thick Film on Beryllia, 2 Conductor Level(s)

**Assembly Information: See Note 1/**

**Assembly Flows:** H1040

**Substrate Attach:** Eutectic, Solder

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Eutectic, Solder

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Tabs

**Wire Bonding:** Gold, Aluminum

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, TO Can, Projection Weld, 2.86 Inch Seal Perimeter, 3 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 4.64 Inch Seal Perimeter, 6 Leads, Gold/Solder Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Teledyne Microelectronic Technologies (CAGE Code: 16170)**

1425 Higgs Road, Lewisburg, TN 37091, US

**Company Contact:** Mr. Evon Bennett, Phone: 931-270-2760, Fax: 931-359-2085, E-mail: ebennett@teledyne.com

**DSCC Contact:** Mr. Richard Barker, Phone: 614-692-0596, Fax: 614-692-6942, E-mail: vqh.rb@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Options 1 and 2

**Approved ISO 9000 System:** No

**Technologies:** Data Converters, Linear, Microwave, Custom, Power, RF Microwave

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**Qualification Letters:** VQ(VQH-14-027666), VQ(VQH-14-027714)

**Class Level Information: See Note 6/**

Class K, Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Purchased Thin Film on Alumina, 3 Conductor Level(s), Resistors

**Assembly Information: See Note 1/**

**Assembly Flows:** 7700530

**Substrate Attach:** Conductive Epoxy

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy

**Add-on Elements:** Unpackaged Die, Chip Resistors, Chip Capacitors

**Wire Bonding:** Gold, Aluminum

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal/Ceramic Co-Fire Package, Peripheral Leads, Seam Weld, 3.94 Inch Seal Perimeter, 40 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Dual-in-Line, Seam Weld, 2.60 Inch Seal Perimeter, 14 Leads, Gold Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**Teledyne Microwave Solutions (CAGE Code: 0D4L1)**

1274 Terra Bella Avenue, Mountain View, CA 94043, US

**Company Contact:** Ms. Dory Maciel, Phone: 408-242-0243, Fax: 650-691-9800, E-mail: dory.maciel@teledyne.com

**DSCC Contact:** Mr. Edward Raybould, Phone: 614-692-0582, Fax: 614-692-6942, E-mail: vqh.esr@dla.mil

**Quality Management (QM) Program:** TRB

**Periodic Inspection System:** Option 1

**Approved ISO 9000 System:** No

**Technologies:** RF Cascadable Amplifier, Microwave Cascadable Amplifier, Mixers, Attenuators, Limiters, Switches, Multi-function

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**Qualification Letters:** VQ(VQH-00-0037), VQ(VQH-01-0128), VQ(VQH-13-026904)

**Class Level Information: See Note 6/**

Class K, Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** N/A

**Substrate Fabrication:** Purchased Thin Film

**Assembly Information: See Note 1/**

**Assembly Flows:** 351393

**Substrate Attach:** Solder

**Element Attach:** Conductive Epoxy, Nonconductive Epoxy, Solder, Eutectic

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Inductors

**Wire Bonding:** Gold, Copper

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, TO Can, Projection Weld, 1.37 Inch Seal Perimeter, 4 Leads, Gold Lead Finish; Metal Package, Flatpack, Seam Weld, 2.13 Inch Seal Perimeter, 4 Leads, Gold Lead Finish; Metal/Ceramic Package, SMT0, Seam Weld, 2.13 Inch Seal Perimeter, 4 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

**VPT Inc/Delta Electronics (CAGE Code: 0ZBZ6)**

1971 Kraft Dr Ste 1000, Blacksburg, VA 24060, US

**Company Contact:** Mr. Shawn Graham, Phone: 540-552-5000 x7566, Fax: 540-552-5003, E-mail: sgraham@vptpower.com

**DSCC Contact:** Ms. Binh Tonnu, Phone: 614-692-0586, Fax: 614-692-6942, E-mail: vqh.bt@dla.mil

**Quality Management (QM) Program:** Non-TRB

**Periodic Inspection System:** Option 1

**Approved ISO 9000 System:** No

**Technologies:** DC/DC Converters, Filters

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**Delta Electronics, Inc Taoyuan Shien, Taiwan Plant**

**Qualification Letters:** VQ(VQH-03-3408), VQ(VQH-05-007383), VQ(VQH-06-009911), VQ(VQH-06-010083), VQ(VQH-06-010462), VQ(VQH-06-010463), VQ(VQH-06-010748), VQ(VQH-07-012667), VQ(VQH-08-014580), VQ(VQH-09-017993), VQ(VQH-09-017994), VQ(VQH-11-022477), VQ(VQH-11-022562), VQ(VQH-12-024201), VQ(VQH-12-024839), VQ(VQH-13-025426), VQ(VQH-13-025533), VQ(VQH-13-025534), VQ(VQH-13-025667), VQ(VQH-13-025769), VQ(VQH-13-025866), VQ(VQH-13-025867), VQ(VQH-13-026652), VQ(VQH-13-026658), VQ(VQH-13-026974), VQ(VQH-13-026992), VQ(VQH-14-027651), VQ(VQH-14-027888), VQ(VQH-14-027889), VQ(VQH-14-027890), VQ(VQH-14-027891), VQ(VQH-14-028197), VQ(VQH-14-028377)

**Class Level Information: See Note 6/**

Class K, Class H, Class E

**Substrate Fabrication Information: See Note 1/**

**Substrate Fabrication Flows:** MFG-001

**Substrate Fabrication:** Thick Film on Alumina, 4 Conductor Level(s), Resistors; Thick Film on Alumina, 1 Conductor Level(s), Resistors; Thick Film on Alumina, 4 Conductor Level(s)

**Assembly Information: See Note 1/**

**Assembly Flows:** MFG-001

**Substrate Attach:** Solder

**Element Attach:** Conductive Epoxy, Solder, Nonconductive Epoxy, RTV

**Add-on Elements:** Unpackaged Die, Chip Capacitors, Chip Resistors, Magnetics, Bonding Chip, Copper Straps, Flexible Circuits, Wirewound Resistor

**Wire Bonding:** Aluminum, Gold

**Package Information: See Notes 1/ 2/ 3/**

**Package Information:** Metal Package, Dual-in-line, Projection Weld, 5.14 Inch Seal Perimeter, 9 Leads, Gold Lead Finish; Metal Package, Dual-in-line, Bathtub, Seam Weld, 6.44 Inch Seal Perimeter, 10 Leads, Gold Lead Finish; Metal Package, Peripheal Leads, Bathtub, Seam Weld, 8.00 Inch Seal Perimeter, 12 Leads, Gold Lead Finish

**Standardized Microcircuit Drawing (SMD) Approved Sources are available at the following web pages:**  
**Qualification Part Search:** <http://www.landandmaritime.dla.mil/programs/psearch/>  
**Standard Microcircuit Cross-Reference:** <http://www.landandmaritime.dla.mil/Programs/Smcr/>  
**Qualified Products Database:** <http://qpldocs.dla.mil/search/parts.aspx?qpl=1116>